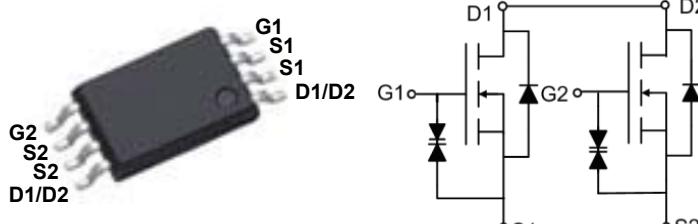


General Description

These N-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

TSSOP8 Dual Pin Configuration



BVDSS	RDS(ON)	ID
20V	12mΩ	7.5A

Features

- 20V, 7.5A, $RDS(ON)=12m\Omega @ VGS=4.5V$
- Improved dv/dt capability
- Fast switching
- Green Device Available
- Suit for 1.8V Gate Drive Applications
- G-S ESD protection diode embedded

Applications

- Notebook
- Load Switch
- LED applications



Absolute Maximum Ratings $T_c=25^\circ C$ unless otherwise noted

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	20	V
V_{GS}	Gate-Source Voltage	± 10	V
I_D	Drain Current – Continuous ($T_c=25^\circ C$)	7.5	A
	Drain Current – Continuous ($T_c=100^\circ C$)	4.7	A
I_{DM}	Drain Current – Pulsed ¹	30	A
P_D	Power Dissipation ($T_c=25^\circ C$)	1.25	W
	Power Dissipation – Derate above $25^\circ C$	0.01	W/ $^\circ C$
T_{STG}	Storage Temperature Range	-55 to 150	$^\circ C$
T_J	Operating Junction Temperature Range	-55 to 150	$^\circ C$

Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction to ambient	---	100	$^\circ C/W$

Electrical Characteristics ($T_J=25^\circ\text{C}$, unless otherwise noted)
Off Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV_{DSS}	Drain-Source Breakdown Voltage	$\text{V}_{\text{GS}}=0\text{V}$, $\text{I}_D=250\mu\text{A}$	20	---	---	V
$\Delta \text{BV}_{\text{DSS}}/\Delta T_J$	BV_{DSS} Temperature Coefficient	Reference to 25°C , $\text{I}_D=1\text{mA}$	---	0.02	---	$\text{V}/^\circ\text{C}$
I_{DSS}	Drain-Source Leakage Current	$\text{V}_{\text{DS}}=20\text{V}$, $\text{V}_{\text{GS}}=0\text{V}$, $T_J=25^\circ\text{C}$	---	---	1	μA
		$\text{V}_{\text{DS}}=16\text{V}$, $\text{V}_{\text{GS}}=0\text{V}$, $T_J=125^\circ\text{C}$	---	---	10	μA
I_{GSS}	Gate-Source Leakage Current	$\text{V}_{\text{GS}}=\pm 10\text{V}$, $\text{V}_{\text{DS}}=0\text{V}$	---	---	± 10	μA

On Characteristics

$\text{R}_{\text{DS(ON)}}$	Static Drain-Source On-Resistance	$\text{V}_{\text{GS}}=4.5\text{V}$, $\text{I}_D=5\text{A}$	7	10	12	$\text{m}\Omega$
		$\text{V}_{\text{GS}}=2.5\text{V}$, $\text{I}_D=3\text{A}$	8	11	14	
		$\text{V}_{\text{GS}}=1.8\text{V}$, $\text{I}_D=2\text{A}$	9	13	20	
$\text{V}_{\text{GS(th)}}$	Gate Threshold Voltage	$\text{V}_{\text{GS}}=\text{V}_{\text{DS}}$, $\text{I}_D = 250\mu\text{A}$	0.3	0.6	1	V
$\Delta \text{V}_{\text{GS(th)}}$	$\text{V}_{\text{GS(th)}}$ Temperature Coefficient		---	2	---	
gfs	Forward Transconductance	$\text{V}_{\text{DS}}=10\text{V}$, $\text{I}_S=5\text{A}$	---	11	---	S

Dynamic and switching Characteristics

Q_g	Total Gate Charge ^{2,3}	$\text{V}_{\text{DS}}=10\text{V}$, $\text{V}_{\text{GS}}=4.5\text{V}$, $\text{I}_D=5\text{A}$	---	16.9	26	nC
Q_{gs}	Gate-Source Charge ^{2,3}		---	1.1	3	
Q_{gd}	Gate-Drain Charge ^{2,3}		---	4	7	
$\text{T}_{\text{d(on)}}$	Turn-On Delay Time ^{2,3}	$\text{V}_{\text{DD}}=10\text{V}$, $\text{V}_{\text{GS}}=4.5\text{V}$, $\text{R}_G=25\Omega$ $\text{I}_D=1\text{A}$	---	6.8	13	nS
T_r	Rise Time ^{2,3}		---	20	38	
$\text{T}_{\text{d(off)}}$	Turn-Off Delay Time ^{2,3}		---	41.8	79	
T_f	Fall Time ^{2,3}		---	13.2	25	
C_{iss}	Input Capacitance	$\text{V}_{\text{DS}}=10\text{V}$, $\text{V}_{\text{GS}}=0\text{V}$, $\text{F}=1\text{MHz}$	---	1020	1480	pF
C_{oss}	Output Capacitance		---	160	240	
C_{rss}	Reverse Transfer Capacitance		---	110	160	

Drain-Source Diode Characteristics and Maximum Ratings

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I_s	Continuous Source Current	$\text{V}_G=\text{V}_D=0\text{V}$, Force Current	---	---	7.5	A
I_{SM}	Pulsed Source Current		---	---	30	A
V_{SD}	Diode Forward Voltage	$\text{V}_{\text{GS}}=0\text{V}$, $\text{I}_s=1\text{A}$, $T_J=25^\circ\text{C}$	---	---	1	V

Note :

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2. The data tested by pulsed , pulse width $\leq 300\text{us}$, duty cycle $\leq 2\%$.
3. Essentially independent of operating temperature.

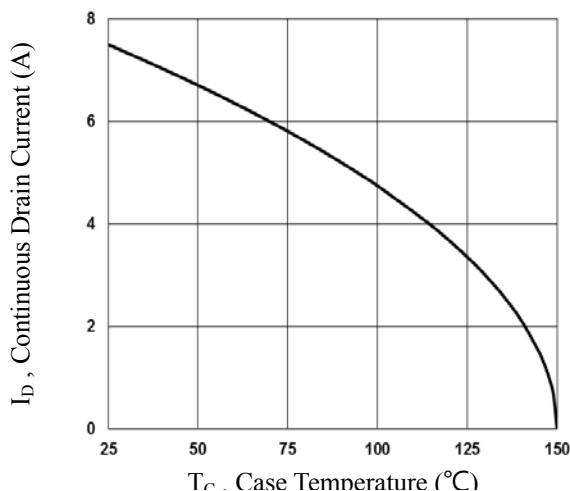


Fig.1 Continuous Drain Current vs. T_C

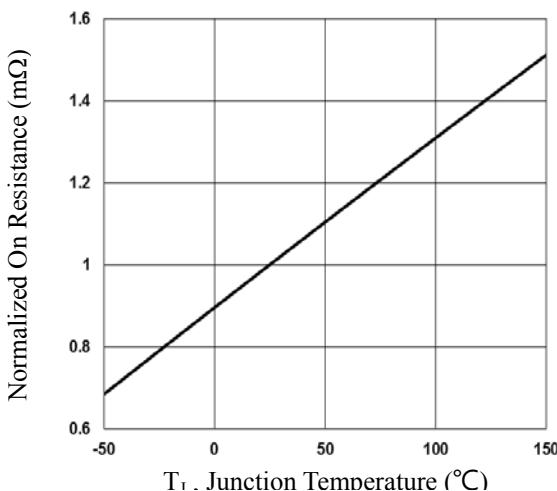


Fig.2 Normalized RD_{SON} vs. T_J

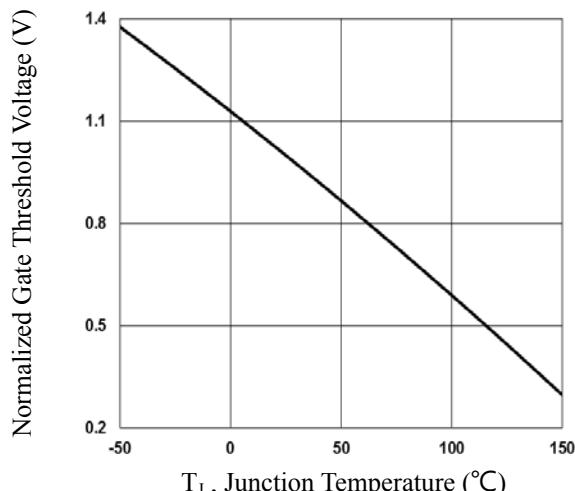


Fig.3 Normalized V_{th} vs. T_J

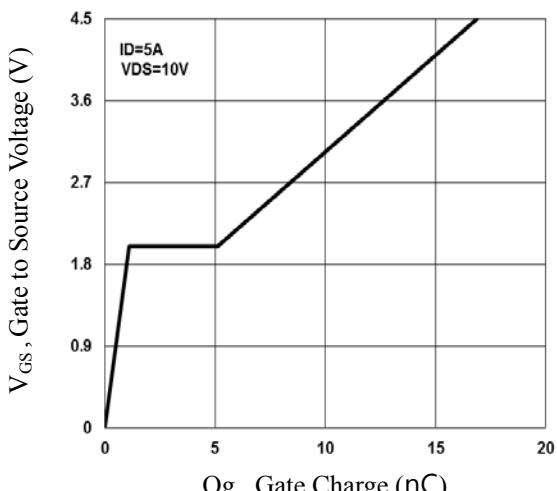


Fig.4 Gate Charge Waveform

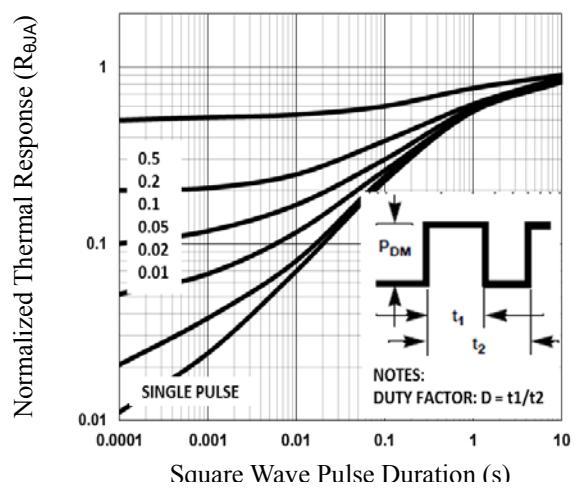


Fig.5 Normalized Transient Impedance

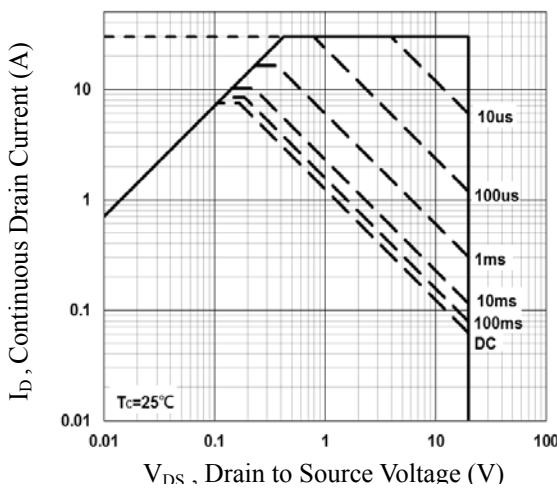


Fig.6 Maximum Safe Operation Area

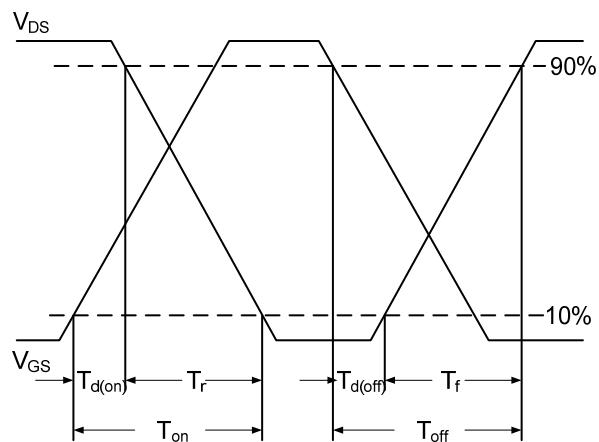


Fig.7 Switching Time Waveform

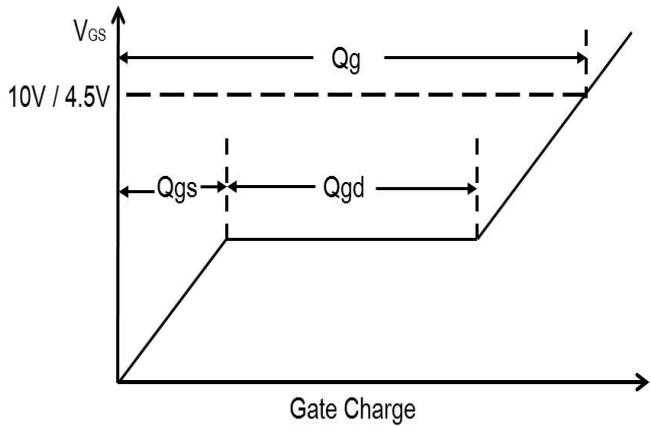
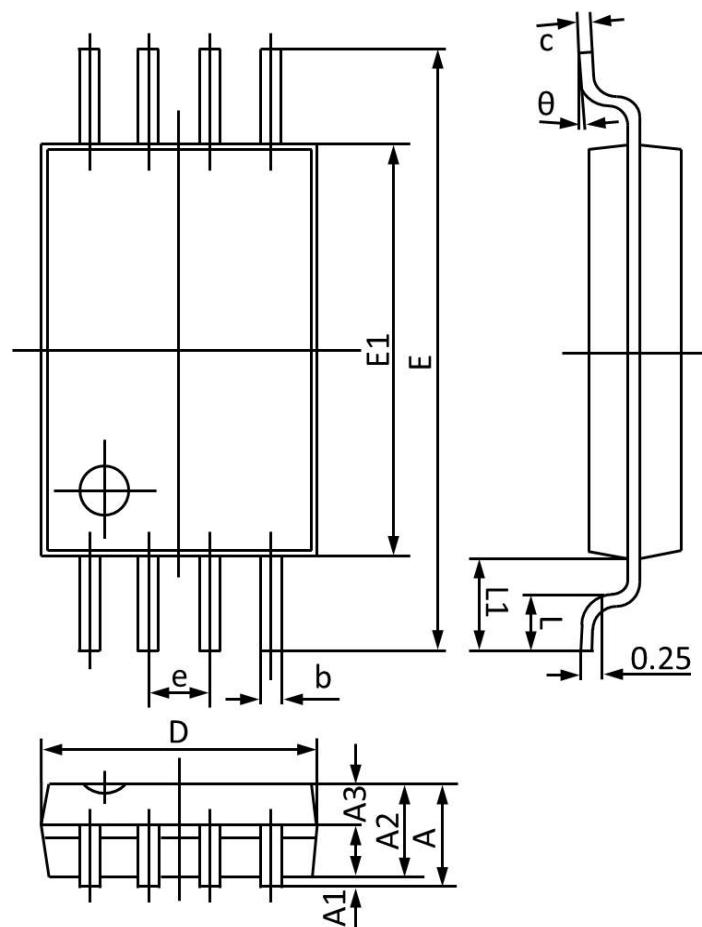


Fig.8 Gate Charge Waveform



TSSOP8 PACKAGE INFORMATION



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	1.100	1.200	0.044	0.047
A1	0.050	0.150	0.002	0.006
A2	0.900	1.050	0.036	0.041
A3	0.390	0.490	0.016	0.019
b	0.210	0.300	0.009	0.011
c	0.130	0.190	0.006	0.007
D	0.120	0.140	0.004	0.006
E	6.200	6.600	0.244	0.260
E1	4.300	4.500	0.169	0.177
e	0.650(BSC)		0.025(BSC)	
L	0.450	0.750	0.018	0.029
L1	1.000(BSC)		0.039(BSC)	
θ	0°	8°	0°	8°